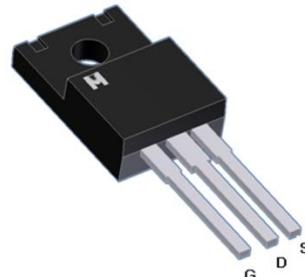
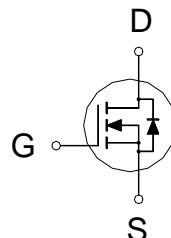


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	150V
R _{DSON} (MAX.)	11.5mΩ
I _D	45A



UIS, R_G 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _C = 25 °C	I _D	45	A
	T _C = 100 °C		28	
Pulsed Drain Current ¹		I _{DM}	180	
Avalanche Current		I _{AS}	30	
Avalanche Energy	L = 0.1mH, ID=30A, RG=25Ω	E _{AS}	45	mJ
Repetitive Avalanche Energy ²	L = 0.05mH	E _{AR}	22.5	
Power Dissipation	T _C = 25 °C	P _D	41	W
	T _C = 100 °C		16	
Operating Junction & Storage Temperature Range		T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}	3.0	62.5	°C / W
Junction-to-Ambient	R _{θJA}			

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0V, I_D = 250\mu\text{A}$	150			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0V, V_{\text{GS}} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 120V, V_{\text{GS}} = 0V$			1	μA
		$V_{\text{DS}} = 100V, V_{\text{GS}} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 10V, V_{\text{GS}} = 10V$	45			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10V, I_D = 20A$		9.3	11.5	$\text{m}\Omega$
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5V, I_D = 20A$		90		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0V, V_{\text{DS}} = 75V, f = 1\text{MHz}$		4805		pF
Output Capacitance	C_{oss}			360		
Reverse Transfer Capacitance	C_{rss}			96		
Gate Resistance	R_g	$V_{\text{GS}} = 15\text{mV}, V_{\text{DS}} = 0V, f = 1\text{MHz}$		1.0		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 75V, V_{\text{GS}} = 10V, I_D = 20A$		75		nC
Gate-Source Charge ^{1,2}	Q_{gs}			16		
Gate-Drain Charge ^{1,2}	Q_{gd}			28		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 75V, I_D = 20A, V_{\text{GS}} = 10V, R_{\text{GS}} = 6\Omega$		22		nS
Rise Time ^{1,2}	t_r			60		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			30		
Fall Time ^{1,2}	t_f			35		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_s				45	A
Pulsed Current ³	I_{SM}				180	
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{\text{GS}} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A/\mu\text{s}$			120	nS
Reverse Recovery Charge	Q_{rr}				375	

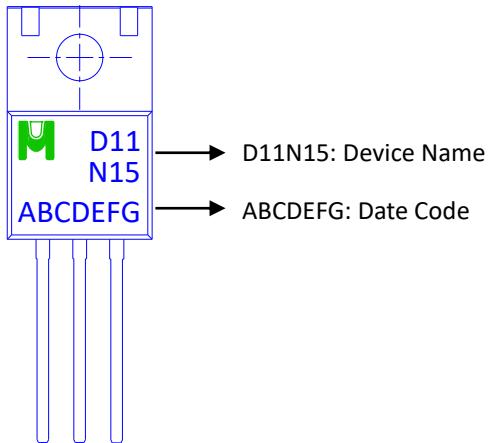
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

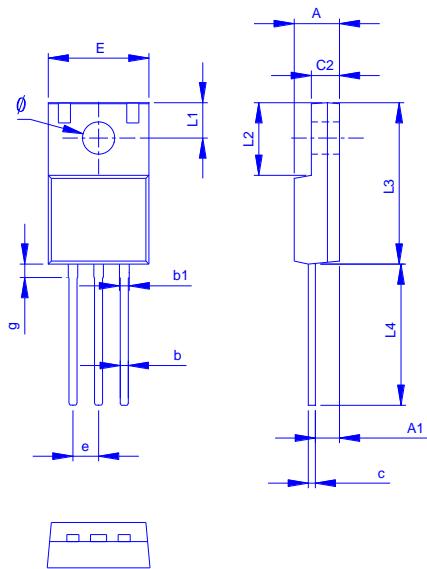
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMD11N15FN for TO-220F



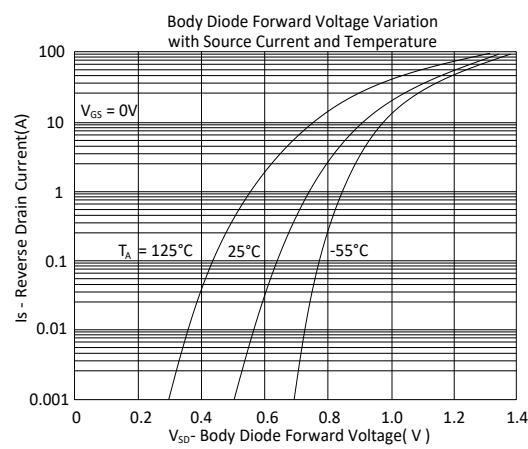
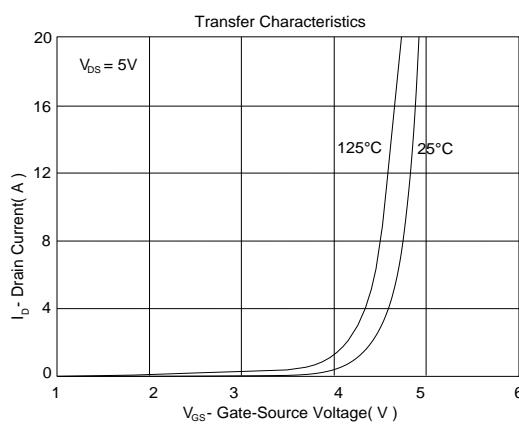
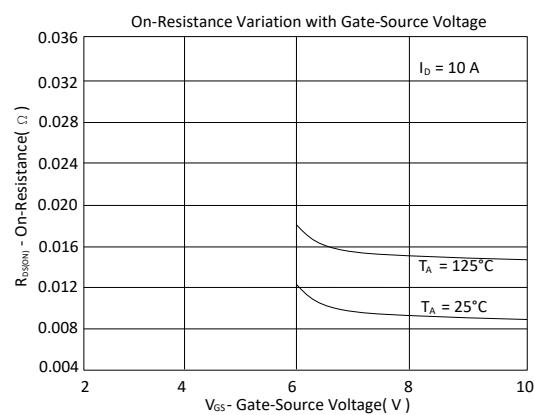
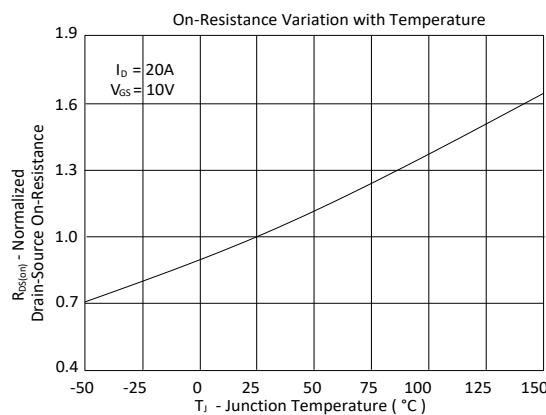
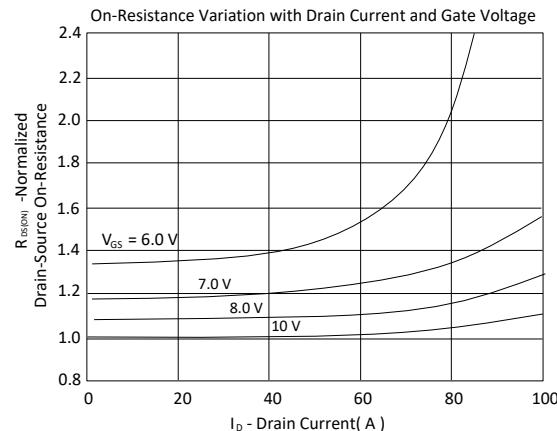
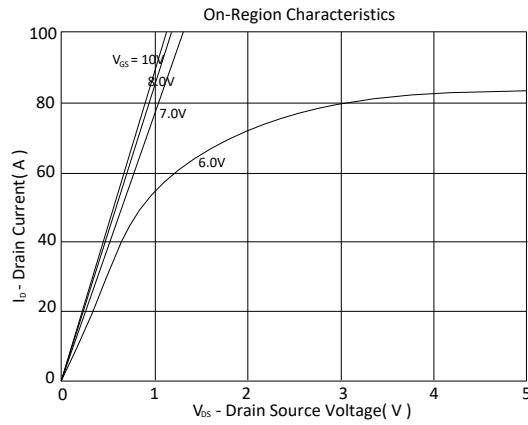
Outline Drawing

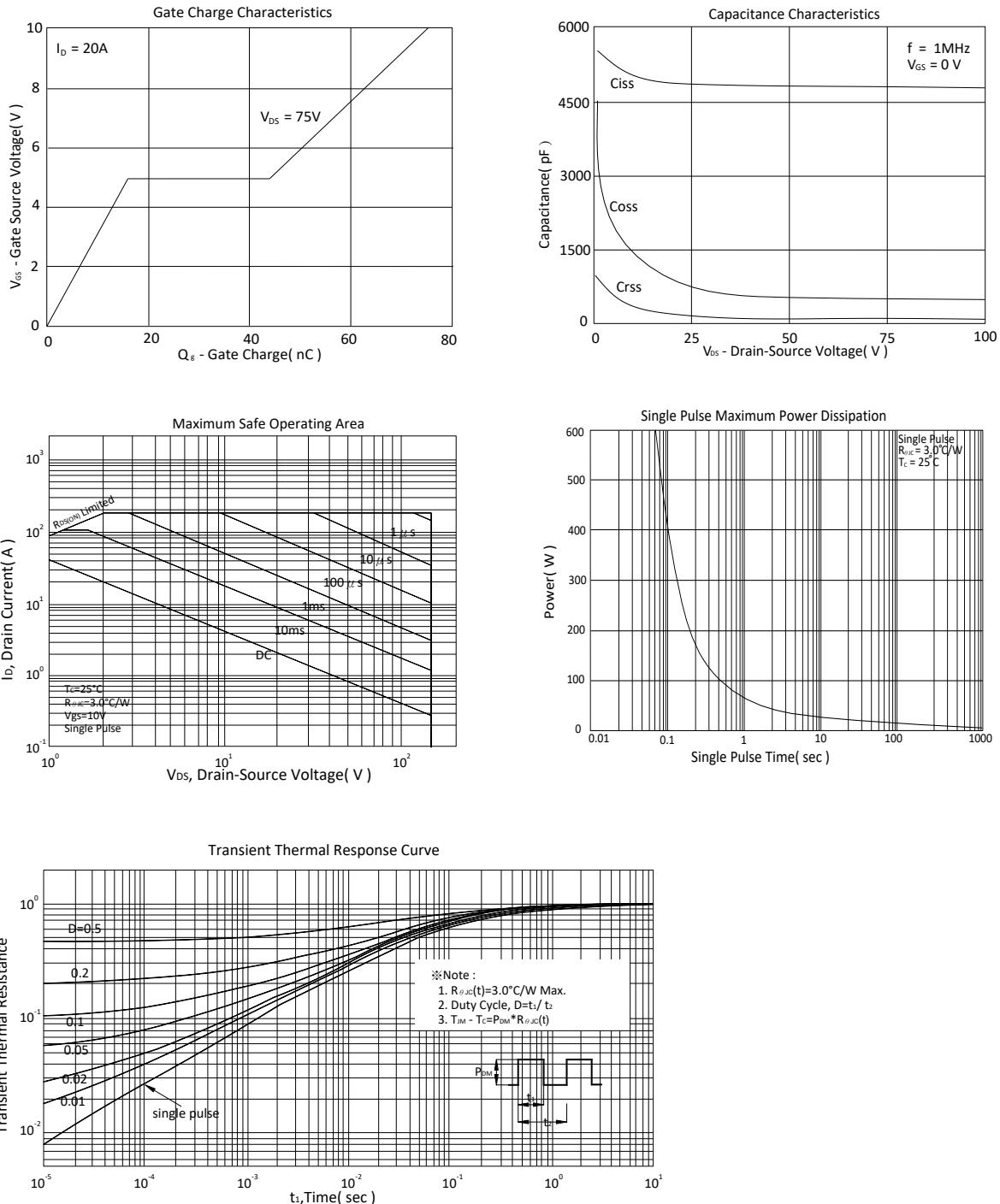


Dimension in mm

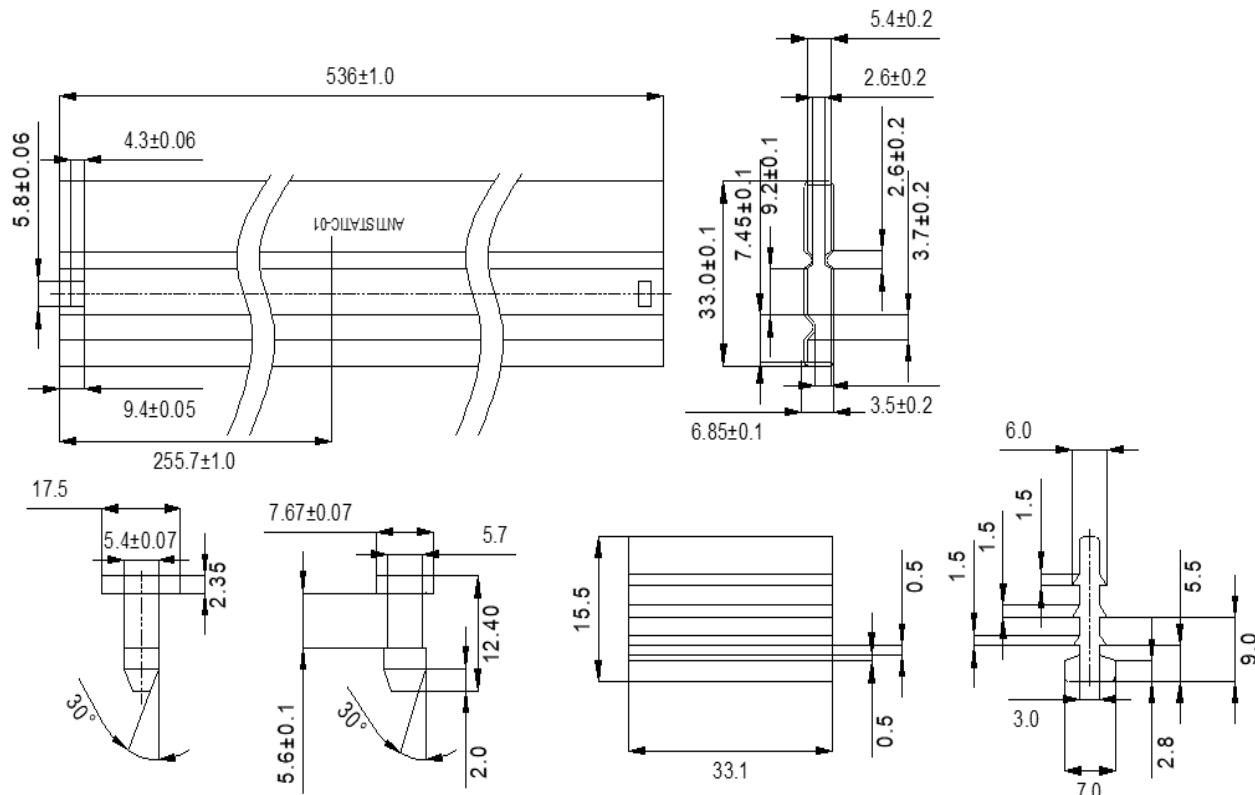
Dimension	A	A1	b	b1	c	c2	E	L1	L2	L3	L4	φ	e	g
Min.	4.30	2.50	0.60	0.60	0.45	2.50	9.70	2.90	6.30	14.70	13.40	3.00	2.35	1.00
Max.	4.70	2.70	0.80	0.90	0.60	2.90	10.30	3.10	6.70	15.30	13.80	3.40	2.75	1.20

TYPICAL CHARACTERISTICS





◆ Tape&Reel Information : 50pcs / Tube (1000pcs/Box)



產品別	TO-220F / TO-220
底塞顏色	白
端塞顏色	藍
裝管方向	Pin 孔朝底塞
裝箱數	
滿管數量	50ea
管/內盒比	20:1
內盒滿箱數	1K
內盒/外箱比	4:1
外箱滿箱數	4K